



Customer Information Notification

202106005I : JN5188(T)/JN5189(T); QN9030/9090(T); K32W041/061;
K32W0421A/AM Datasheet and UserManual Update

Note: This notice is NXP Company
Proprietary.

Issue Date: Jun 25, 2021 **Effective date:** Jun 26, 2021



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Change Category

- | | | | | |
|--|--|--|--|---|
| <input type="checkbox"/> Wafer
Fab
Process | <input type="checkbox"/> Assembly
Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test
Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer
Fab
Materials | <input type="checkbox"/> Assembly
Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test
Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer
Fab
Location | <input type="checkbox"/> Assembly
Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test
Location | <input type="checkbox"/> Electrical
spec./Test
coverage |
| <input type="checkbox"/> Firmware <input checked="" type="checkbox"/> Other: Data Sheet update, User Manual update | | | | |

PCN Overview

Description

NXP announces a datasheet update for the following devices

- JN5188 (T), JN5189(T) to Rev. 1.3
- QN9030(T), QN9090(T) to Rev. 1.2
- K32W041/061 to Rev. 1.3
- K32W041A/AM to Rev. 1.1

The user manuals were updated, too:

- User manual JN5188 (T), JN5189(T) to Rev. 1.5
- User manual QN9030(T), QN9090(T) to Rev. 1.2
- User manual K32W041/061 to Rev. 1.2
- User manual K32W041A/AM to Rev. 1.1

The revision history included in the updated documents provides the link to the changes. Changes are summarized below:

Data Sheet modification:

- Updated Figure 4 “System memory map” for the QSPI.
- Updated BOD as wake-up source to exit Deep sleep and Power-down in Table 8 “Power mode wake-up sources”
- Added ts in the Table 11 “Limiting values”, added Figure 11 “Power-up ramp”, Figure 12 “Minimum VBAT rise time vs temperature”, Figure 13 “Maximum VBAT slope vs temperature”.
- Updated to “8-input 12-bit ADC, 190 ksamples/s (Max.)” in the Section 2.3 “Microcontroller features”.
- Updated to “Conversion rate 190 ksamples/s (Max.) for 12-bit resolution” in the Section 8.15 “12-bit general purpose ADC”.

User Manual modification:

- Updated Table 4 “Pin properties”
- Updated Figure 2 “Main memory map” for the QSPI.
- Updated Table 64 “Available pins and configuration registers”.
- Updated to “12-bit conversion rate of 190 ksamples/s (Max.)” in the Section 27.2 “Features”.

The data sheet revisions as well as the User Manual revisions are attached to this notice, and can be found at www.nxp.com:

<https://www.nxp.com/docs/en/nxp/data-sheets/JN5189.pdf>

[https://www.nxp.com/docs/en/nxp/data-sheets/QN9090\(T\)QN9030\(T\).pdf](https://www.nxp.com/docs/en/nxp/data-sheets/QN9090(T)QN9030(T).pdf)

<https://www.nxp.com/docs/en/data-sheet/K32W061.pdf>

<https://www.nxp.com/docs/en/data-sheet/K32W041AM.pdf>

<https://www.nxp.com/docs/en/nxp/user-guides/UM11138.pdf>

<https://www.nxp.com/docs/en/user-guide/UM11141.pdf>

<https://www.nxp.com/docs/en/user-guide/UM11323.pdf>

<https://www.nxp.com/docs/en/reference-manual/UM11485.pdf>

Reason

- 1) Growing insight after additional measurements at cold temperatures.
- 2) Customer request to connect a 8M flash device to the QSPI.
- 3) Alignment data sheet and user manual.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: [view online](#)

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For specific questions on this notice or the products affected please contact our specialist directly:

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